

# IXTY32P05T Datasheet



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DiGi Electronics Part Number	IXTY32P05T-DG
Manufacturer	<a href="#">IXYS</a>
Manufacturer Product Number	IXTY32P05T
Description	MOSFET P-CH 50V 32A TO252
Detailed Description	P-Channel 50 V 32A (Tc) 83W (Tc) Surface Mount TO-252AA



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## Purchase and inquiry

Manufacturer Product Number:

IXTY32P05T

Series:

TrenchP™

FET Type:

P-Channel

Drain to Source Voltage (Vdss):

50 V

Drive Voltage (Max Rds On, Min Rds On):

10V

Vgs(th) (Max) @ Id:

4.5V @ 250µA

Vgs (Max):

±15V

FET Feature:

-

Operating Temperature:

-55°C ~ 150°C (Tj)

Supplier Device Package:

TO-252AA

Base Product Number:

IXTY32

Manufacturer:

IXYS

Product Status:

Active

Technology:

MOSFET (Metal Oxide)

Current - Continuous Drain (Id) @ 25°C:

32A (Tc)

Rds On (Max) @ Id, Vgs:

39mOhm @ 16A, 10V

Gate Charge (Qg) (Max) @ Vgs:

46 nC @ 10 V

Input Capacitance (Ciss) (Max) @ Vds:

1975 pF @ 25 V

Power Dissipation (Max):

83W (Tc)

Mounting Type:

Surface Mount

Package / Case:

TO-252-3, DPAK (2 Leads + Tab), SC-63

## Environmental & Export classification

RoHS Status:

ROHS3 Compliant

REACH Status:

REACH Unaffected

HTSUS:

8541.29.0095

Moisture Sensitivity Level (MSL):

1 (Unlimited)

ECCN:

EAR99

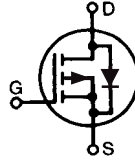


# TrenchP™ Power MOSFET

## IXTY32P05T IXTA32P05T IXTP32P05T

$$\begin{aligned} V_{DSS} &= -50V \\ I_{D25} &= -32A \\ R_{DS(on)} &\leq 39m\Omega \end{aligned}$$

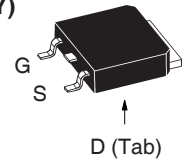
P-Channel Enhancement Mode  
Avalanche Rated



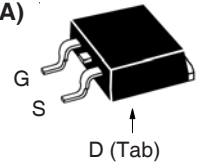
Symbol	Test Conditions	Maximum Ratings	
$V_{DSS}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$	- 50	V
$V_{DGR}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$ , $R_{GS} = 1M\Omega$	- 50	V
$V_{GSS}$	Continuous	$\pm 15$	V
$V_{GSM}$	Transient	$\pm 25$	V
$I_{D25}$	$T_C = 25^\circ\text{C}$	- 32	A
$I_{DM}$	$T_C = 25^\circ\text{C}$ , Pulse Width Limited by $T_{JM}$	-110	A
$I_A$	$T_C = 25^\circ\text{C}$	- 32	A
$E_{AS}$	$T_C = 25^\circ\text{C}$	200	mJ
$P_D$	$T_C = 25^\circ\text{C}$	83	W
$T_J$		-55 ... +150	$^\circ\text{C}$
$T_{JM}$		150	$^\circ\text{C}$
$T_{stg}$		-55 ... +150	$^\circ\text{C}$
$T_L$	Maximum Lead Temperature for Soldering	300	$^\circ\text{C}$
$T_{SOLD}$	1.6 mm (0.062in.) from Case for 10s	260	$^\circ\text{C}$
$M_d$	Mounting Torque (TO-220)	1.13 / 10	Nm/lb.in
<b>Weight</b>	TO-252	0.35	g
	TO-263	2.50	g
	TO-220	3.00	g

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$BV_{DSS}$	$V_{GS} = 0V$ , $I_D = -250\mu\text{A}$	- 50		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = -250\mu\text{A}$	- 2.5		- 4.5 V
$I_{GSS}$	$V_{GS} = \pm 15V$ , $V_{DS} = 0V$			$\pm 50$ nA
$I_{DSS}$	$V_{DS} = V_{DSS}$ , $V_{GS} = 0V$ $T_J = 125^\circ\text{C}$			- 3 $\mu\text{A}$
				-100 $\mu\text{A}$
$R_{DS(on)}$	$V_{GS} = -10V$ , $I_D = 0.5 \cdot I_{D25}$ , Note 1			39 m $\Omega$

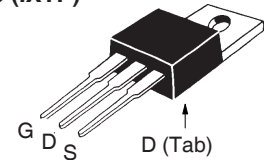
TO-252 (IXTY)



TO-263 (IXTA)



TO-220 (IXTP)



G = Gate      D = Drain  
S = Source    Tab = Drain

### Features

- International Standard Packages
- Avalanche Rated
- Extended FBSOA
- Fast Intrinsic Diode
- Low  $R_{DS(ON)}$  and  $Q_G$

### Advantages

- Easy to Mount
- Space Savings
- High Power Density

### Applications

- High-Side Switching
- Push Pull Amplifiers
- DC Choppers
- Automatic Test Equipment
- Current Regulators
- Battery Charger Applications



IXTY32P05T

IXTA32P05T

IXTP32P05T

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$g_{fs}$	$V_{DS} = -10\text{V}$ , $I_D = 0.5 \cdot I_{D25}$ , Note 1	11	17	S
$C_{iss}$	$V_{GS} = 0\text{V}$ , $V_{DS} = -25\text{V}$ , $f = 1\text{MHz}$		1975	pF
$C_{oss}$			315	pF
$C_{rss}$			160	pF
$t_{d(on)}$	<b>Resistive Switching Times</b> $V_{GS} = -10\text{V}$ , $V_{DS} = -30\text{V}$ , $I_D = 0.5 \cdot I_{D25}$ $R_G = 10\Omega$ (External)		20	ns
$t_r$			28	ns
$t_{d(off)}$			39	ns
$t_f$			27	ns
$Q_{g(on)}$	$V_{GS} = -10\text{V}$ , $V_{DS} = 0.5 \cdot V_{DSS}$ , $I_D = 0.5 \cdot I_{D25}$		46	nC
$Q_{gs}$			19	nC
$Q_{gd}$			11	nC
$R_{thJC}$	TO-220			1.5 $^\circ\text{C/W}$
$R_{thCS}$		0.50		$^\circ\text{C/W}$

#### Source-Drain Diode

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$I_S$	$V_{GS} = 0\text{V}$			-32 A
$I_{SM}$	Repetitive, Pulse Width Limited by $T_{JM}$			-128 A
$V_{SD}$	$I_F = I_S$ , $V_{GS} = 0\text{V}$ , Note 1			-1.5 V
$t_{rr}$	$I_F = 0.5 \cdot I_{D25}$ , $-di/dt = -100\text{A}/\mu\text{s}$ $V_R = -25\text{V}$ , $V_{GS} = 0\text{V}$		26	ns
$Q_{RM}$			21	nC
$I_{RM}$			-1.6	A

Note 1: Pulse test,  $t \leq 300\mu\text{s}$ , duty cycle,  $d \leq 2\%$ .

IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:	4,835,592	4,931,844	5,049,961	5,237,481	6,162,665	6,404,065B1	6,683,344	6,727,585	7,005,734B2	7,157,338B2
	4,860,072	5,017,508	5,063,307	5,381,025	6,259,123B1	6,534,343	6,710,405B2	6,759,692	7,063,975B2	
	4,881,106	5,034,796	5,187,117	5,486,715	6,306,728B1	6,583,505	6,710,463	6,771,478B2	7,071,537	

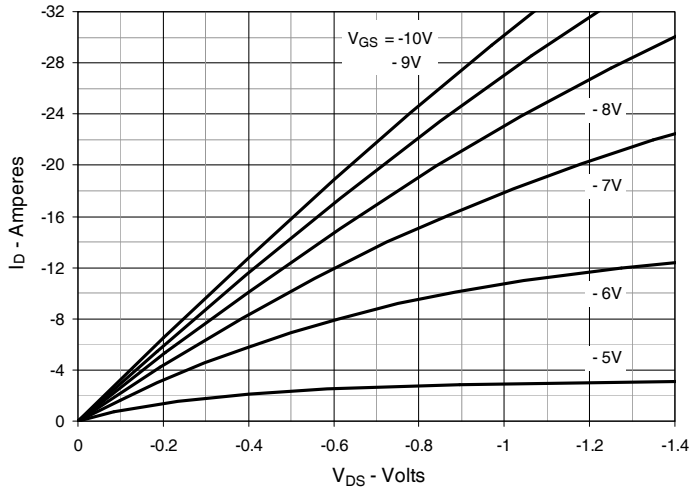
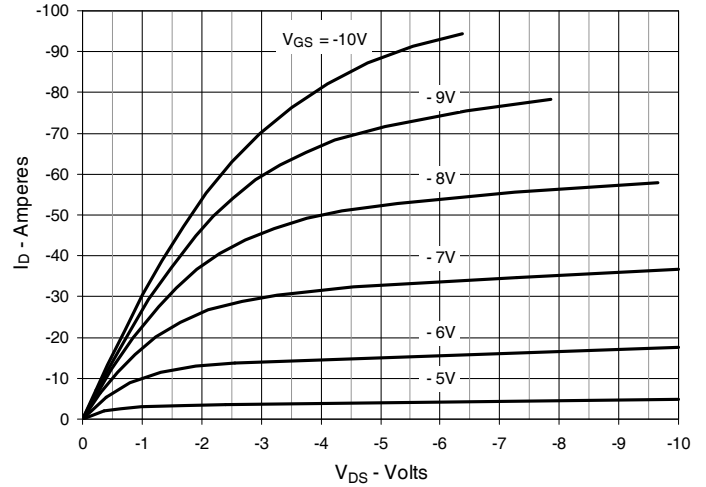
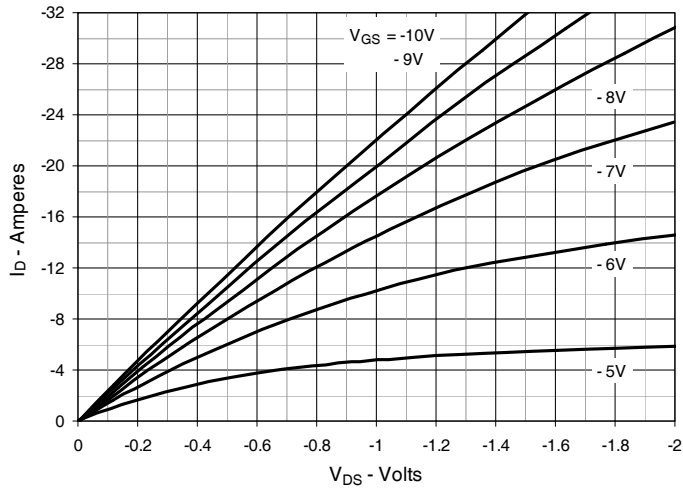
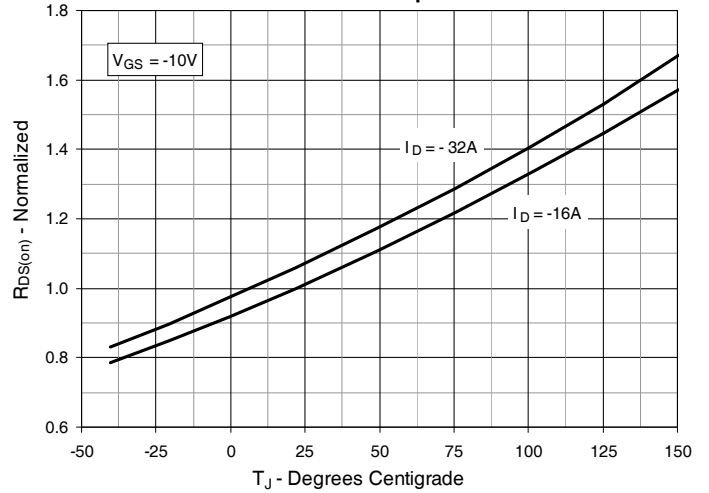
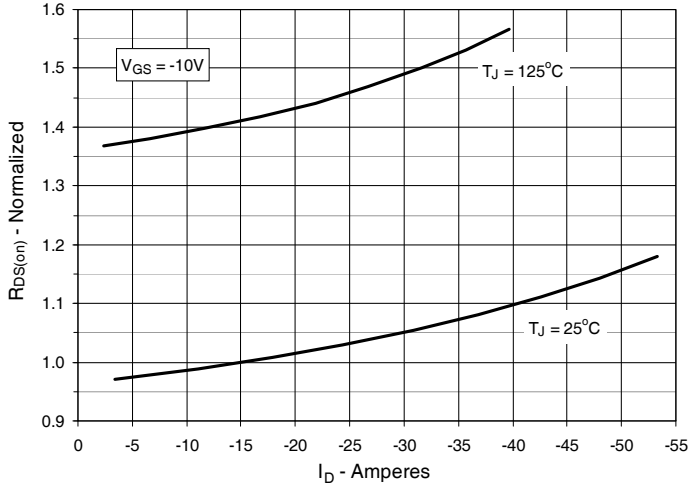
Fig. 1. Output Characteristics @  $T_J = 25^\circ\text{C}$ Fig. 2. Extended Output Characteristics @  $T_J = 25^\circ\text{C}$ Fig. 3. Output Characteristics @  $T_J = 125^\circ\text{C}$ Fig. 4.  $R_{DS(on)}$  Normalized to  $I_D = -16\text{A}$  Value vs. Junction TemperatureFig. 5.  $R_{DS(on)}$  Normalized to  $I_D = -16\text{A}$  Value vs. Drain Current

Fig. 6. Maximum Drain Current vs. Case Temperature

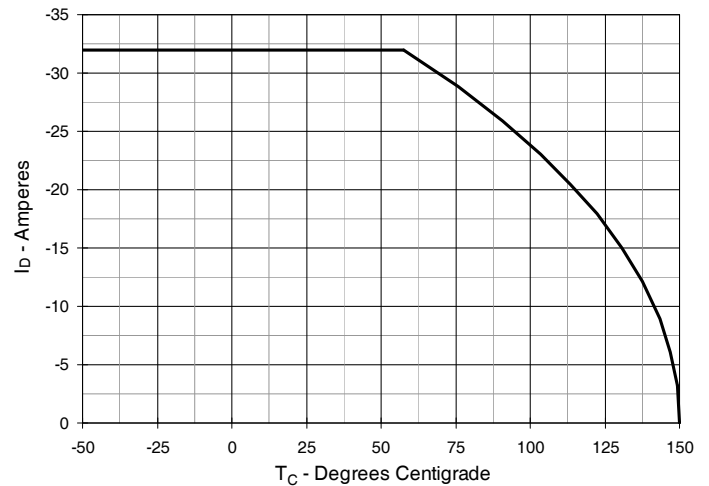


Fig. 7. Input Admittance

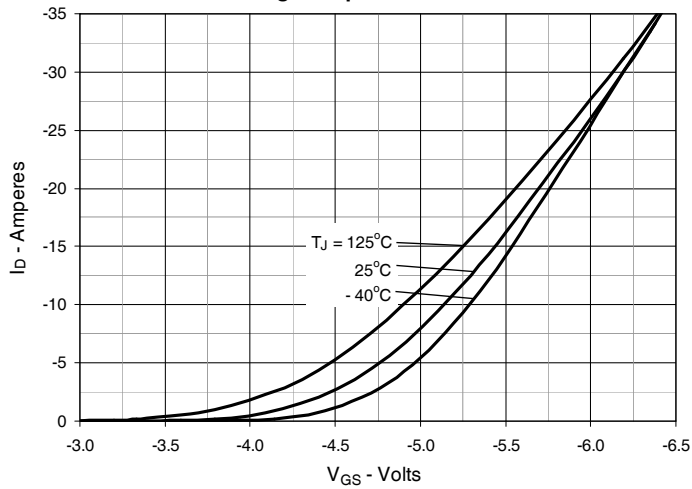


Fig. 8. Transconductance

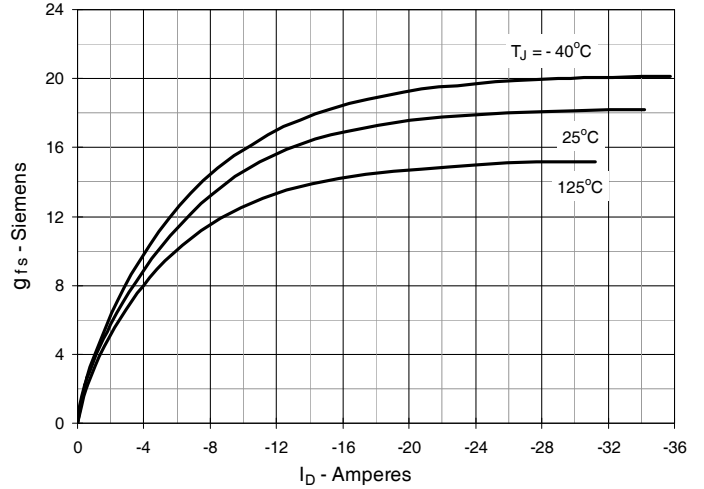


Fig. 9. Forward Voltage Drop of Intrinsic Diode

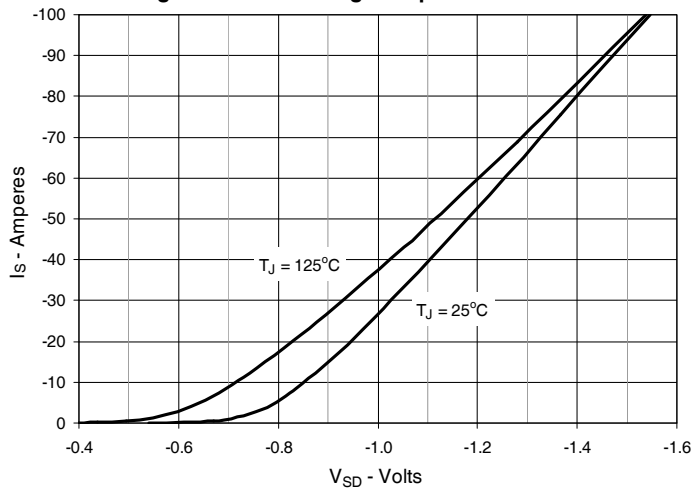


Fig. 10. Gate Charge

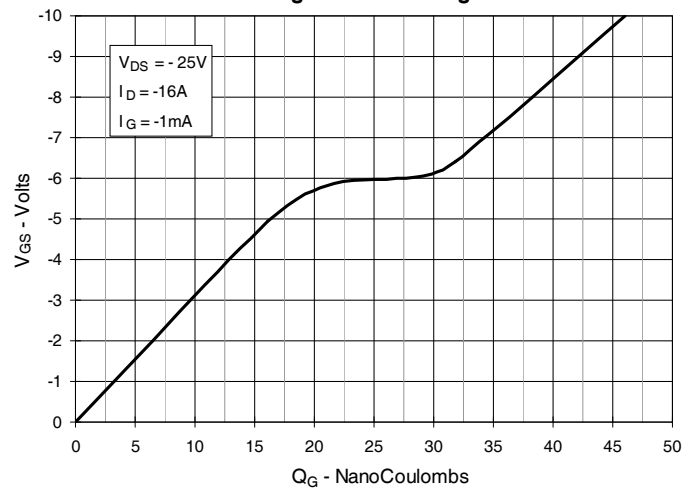


Fig. 11. Capacitance

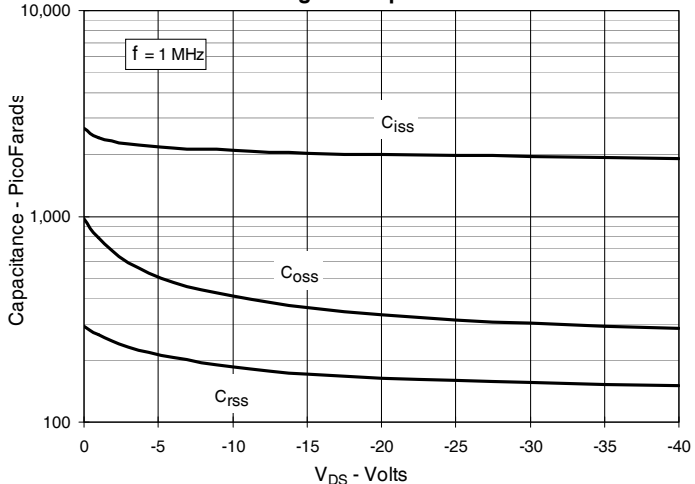


Fig. 12. Forward-Bias Safe Operating Area

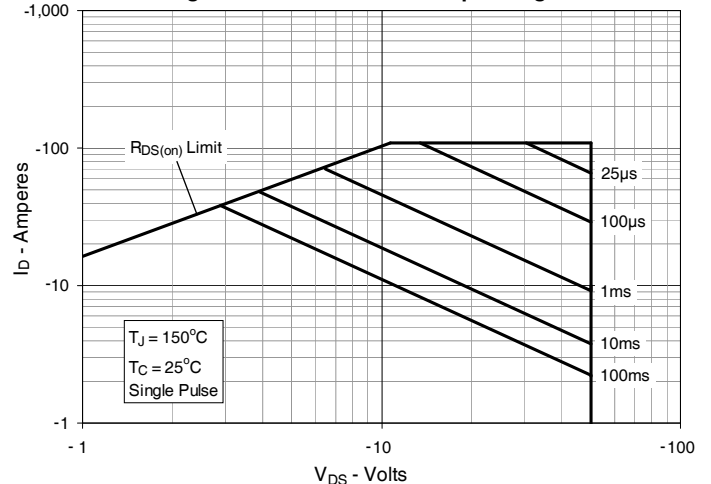


Fig. 13. Resistive Turn-on Rise Time vs. Junction Temperature

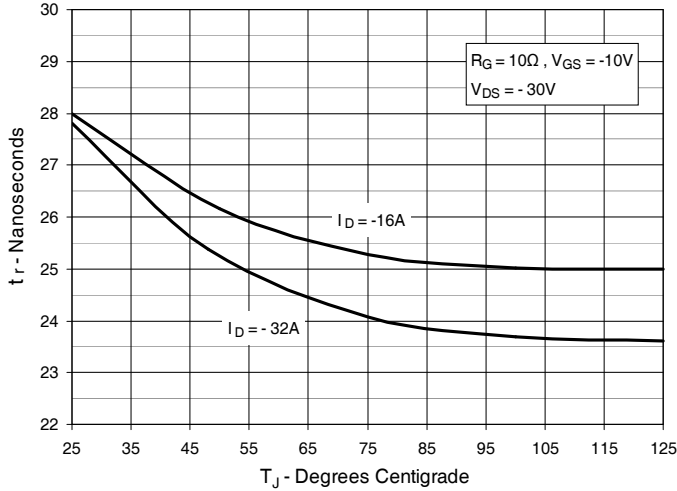


Fig. 14. Resistive Turn-on Rise Time vs. Drain Current

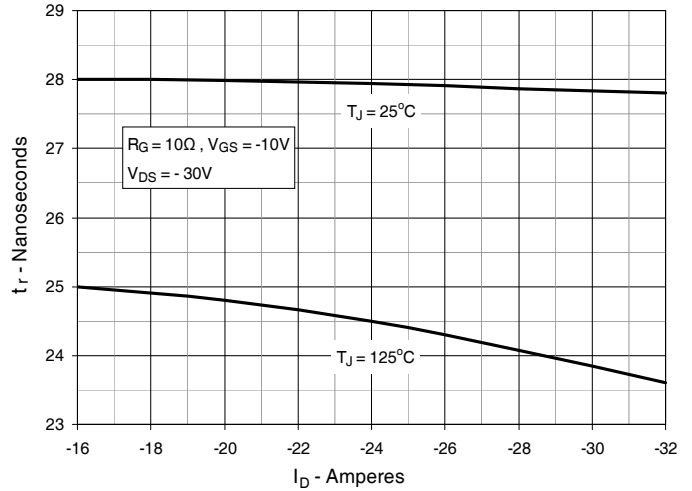


Fig. 15. Resistive Turn-on Switching Times vs. Gate Resistance

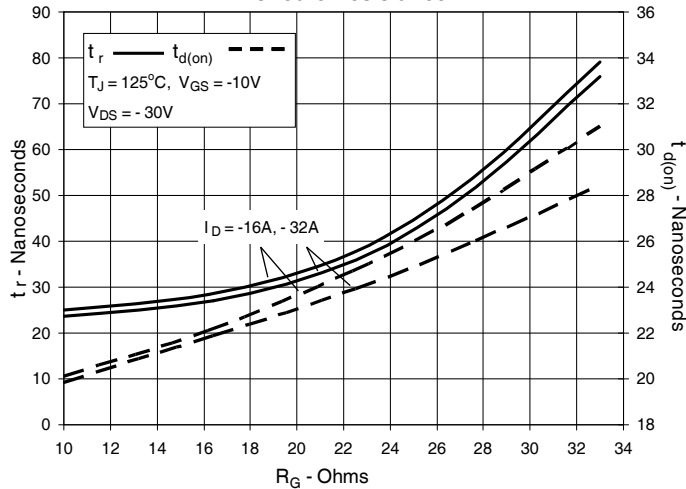


Fig. 16. Resistive Turn-off Switching Times vs. Junction Temperature

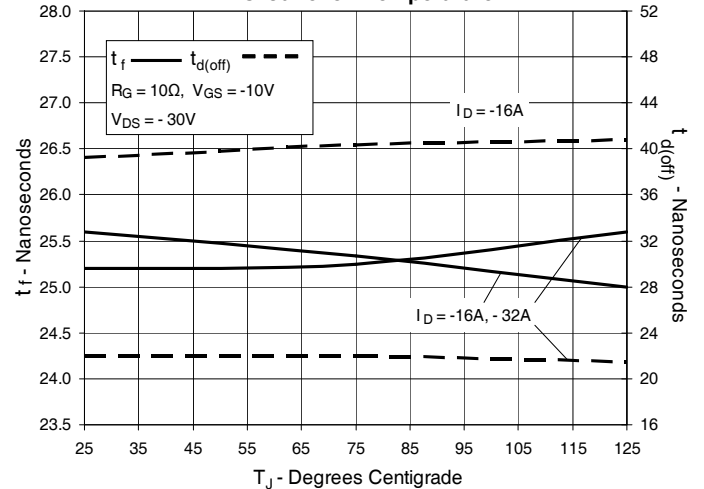


Fig. 17. Resistive Turn-off Switching Times vs. Drain Current

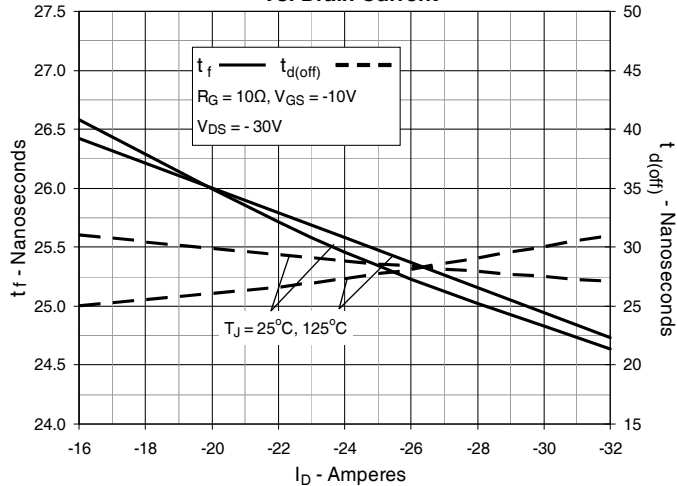


Fig. 18. Resistive Turn-off Switching Times vs. Gate Resistance

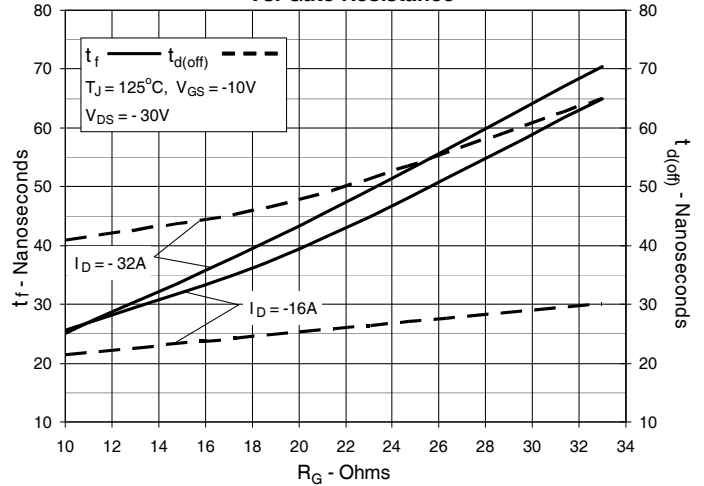
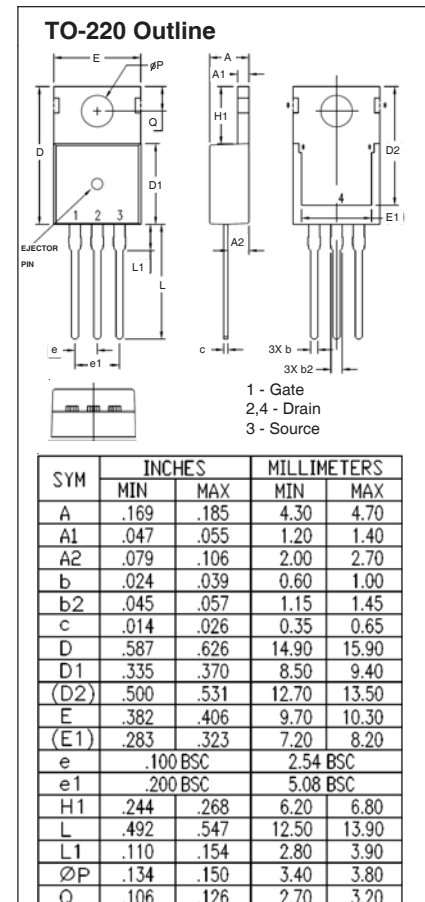
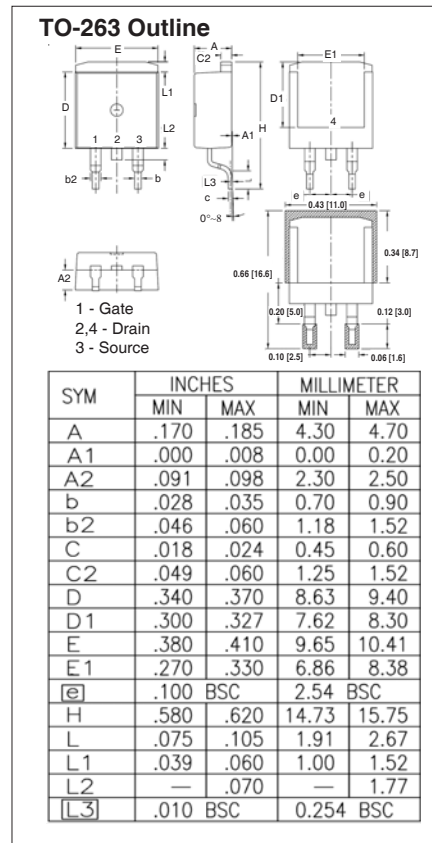
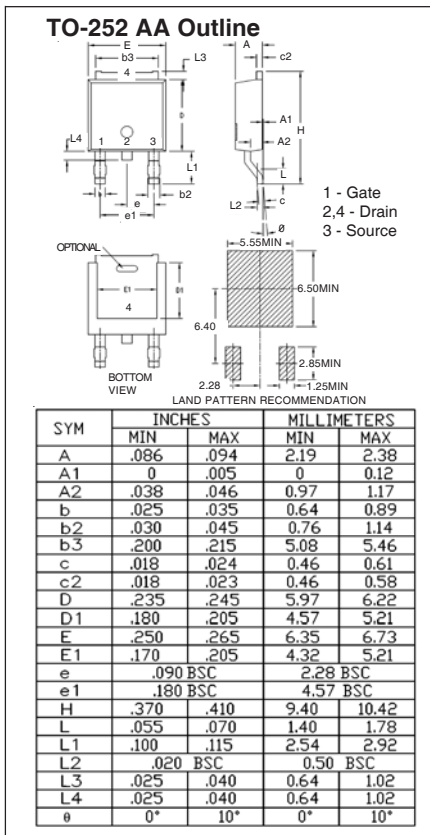
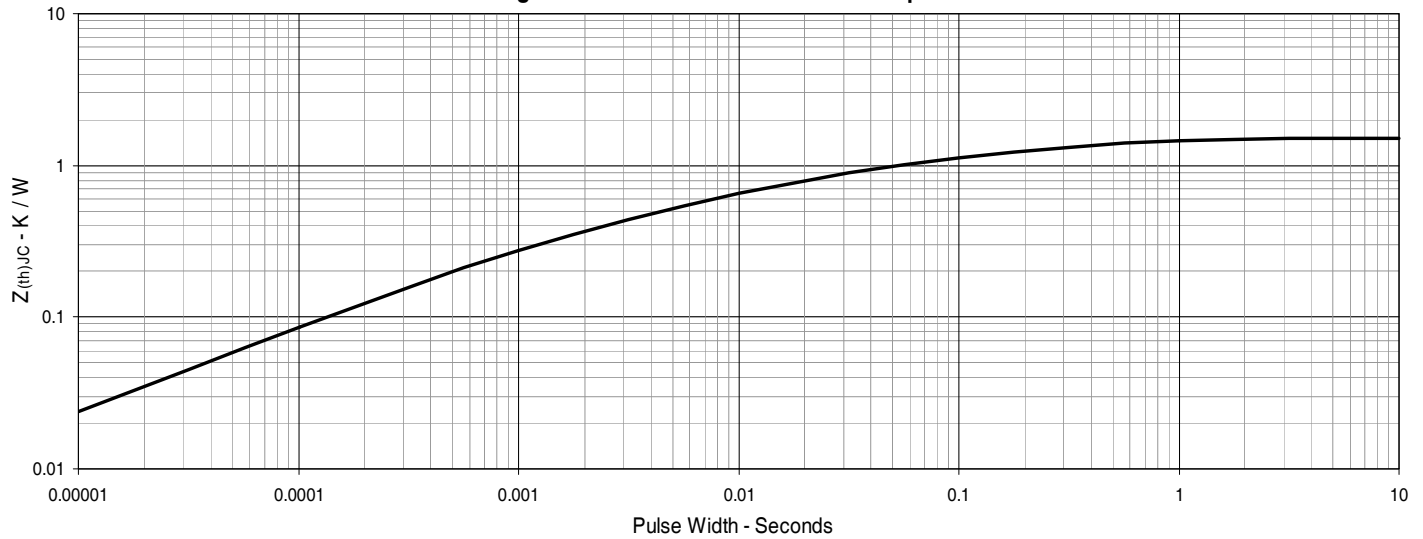


Fig. 19. Maximum Transient Thermal Impedance



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